

**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No.: 09/114,665  
Filing Date: July 13, 1998  
Applicant: Thomas R. Bieler, et al.  
Group Art Unit: 1742  
Examiner: I.P. Sikyin  
Title: METHODS FOR PRODUCING LEAD-FREE IN-SITU COMPOSITE SOLDER ALLOYS  
Attorney Docket: 6550-000013

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Commissioner of Patents and Trademarks  
Washington, D.C. 20231

**AMENDMENT UNDER 37 C.F.R. §1.111**

Dear Sir:

In response to the Office Action mailed July 16, 2001, please enter the following amendments and consider the accompanying remarks.

**IN THE CLAIMS**

Please cancel Claims 1-11, and 13-25, without prejudice. Please add the following new claims 26-58.

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26. (new) A method for producing an *in-situ* composite solder having an intermetallic component, comprising the steps of:

(a) providing a matrix solder comprising two or more metals;

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